Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
DL365 G1, All Models

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	9
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screwdriver	T-15
Phillips Screwdriver	# 2
Flat Head Screwdriver	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Capacitors > 2.5CM – Remove the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover and the heatsinks in the P/S then locate the capacitor and pry it from the PCB with a medium flat head screw driver and dispose of properly. Note that this product utilizes two different power supply vendors and the capacitor location is different for each. Both locations are shown in Attachment 1
2. BBWC Battery – The BBWC is optional and if installed it resides in a pocket in front of the center fan module 2 and above SAS/SATA drive bay #3. Actuate the retention lever and slide the battery tray out, detach the battery assembly from the battery cable, and dispose of the battery properly.
3. System Board Battery – Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly
4.
5.
6.
7.
8.

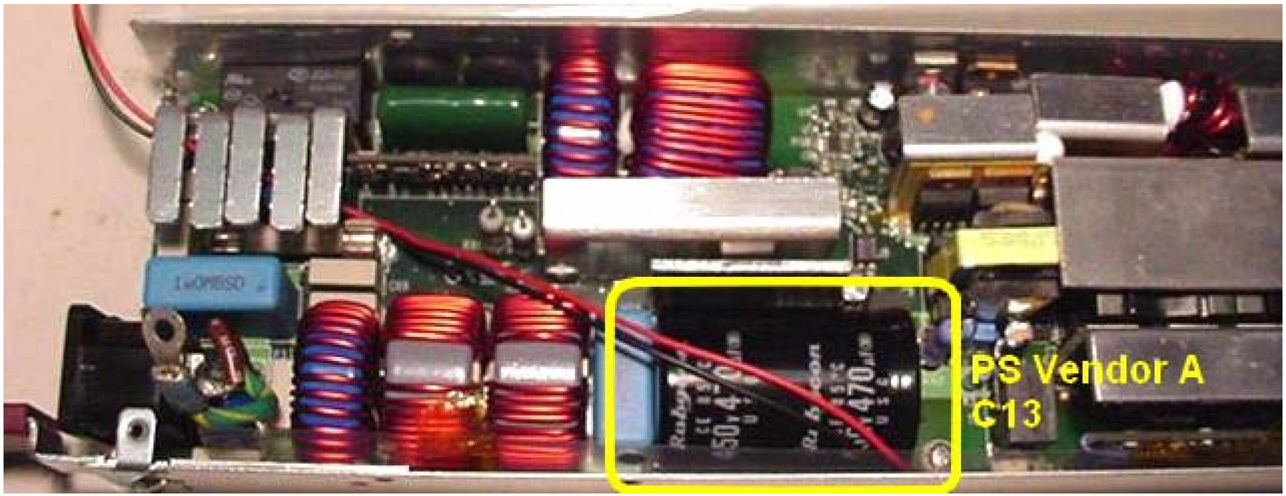
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

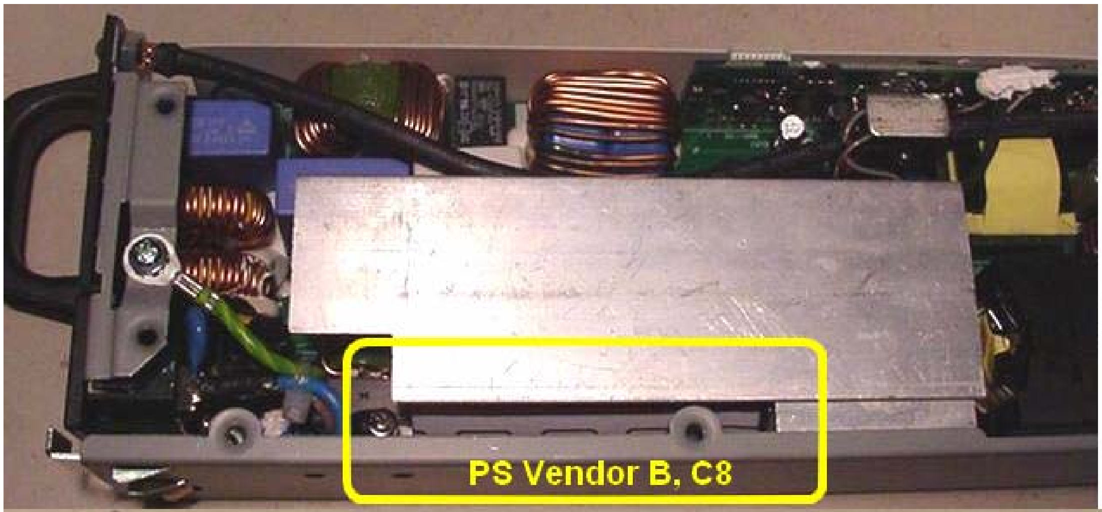
Attachment 1 – Power Supply Capacitor Locations

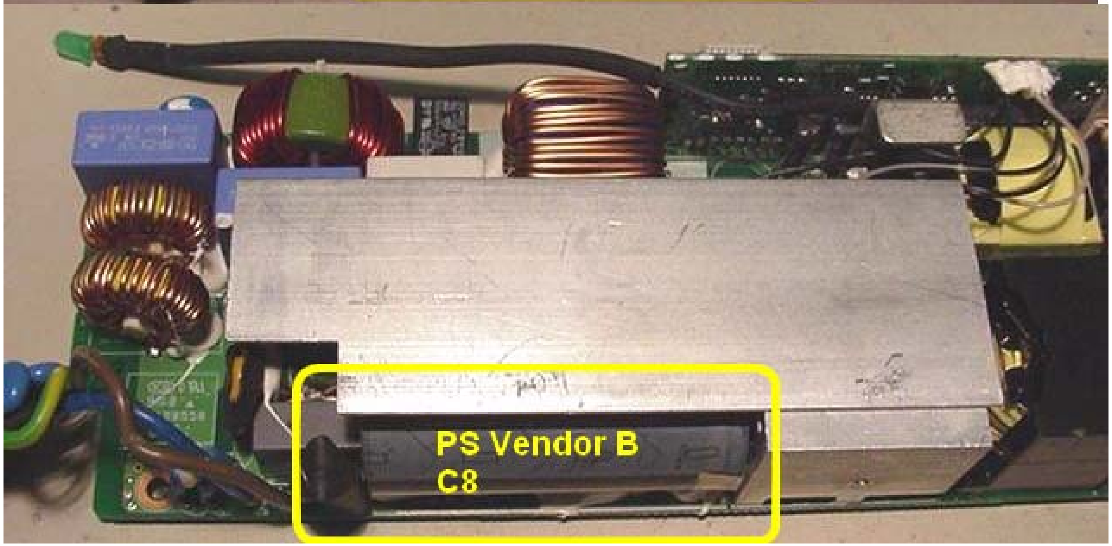
Attachment 2 – BBWC Battery Location

Attachment 3 – System Battery Location

Attachment 1

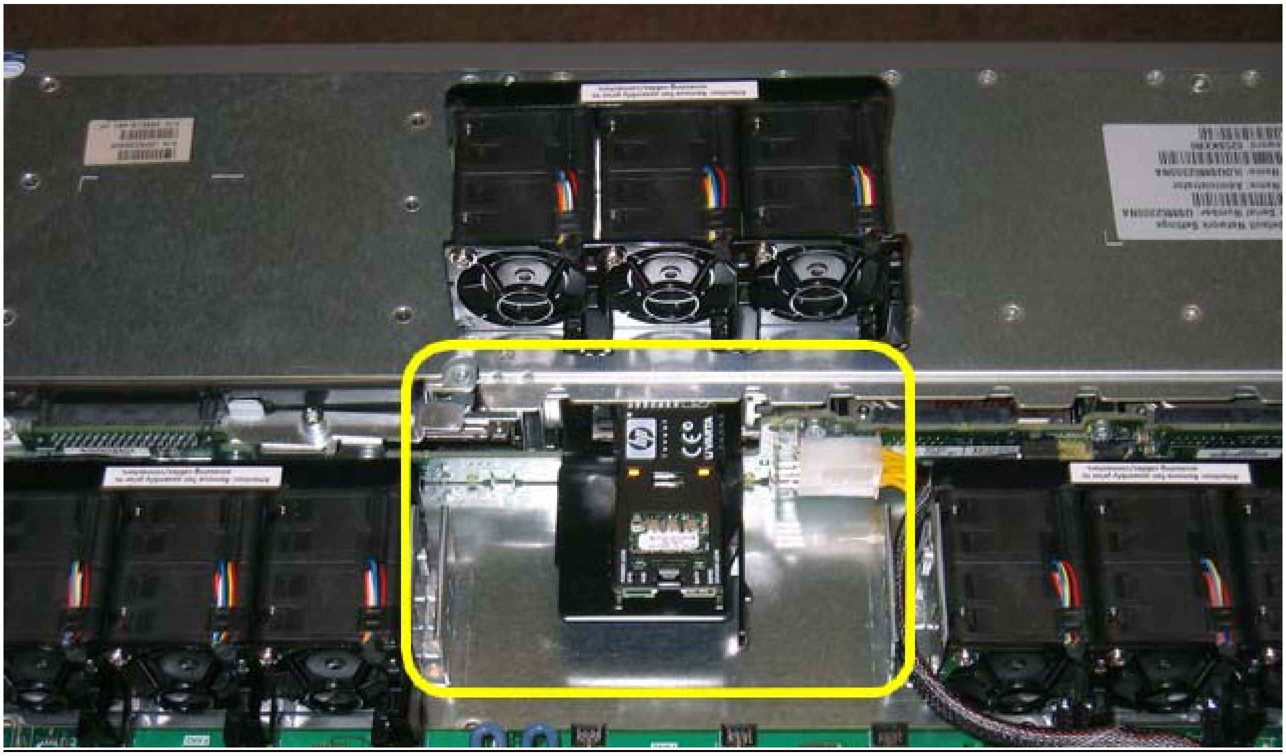






Attachment 2

The BBWC is optional and if installed it resides in a pocket in front of the center fan module 2 and above SAS/SATA drive bay #3.



Attachment 3